

Lead-Free Solders Workshop 2005 - TMS Annual Meeting 2005, San Fancisco, CA,

February 13, 2005

Provided Courtesy of Materials Technology@TMS



PRESENTATION TITLE Opening Remarks: TMS Workshop of Pb-Free	AUTHOR(S) Ravi Mahajan	MORE View Presentation
Uses and Risks of Lead in Products - Summary of Policy Study for the EC	Arnold Tucker	View Presentation
Impacts of RoHS (e.g., Pb) on Electronic Products	John H. Lau	View Presentation
Lead-Free Flip Chip Technology Potentials and Pitfalls	Roger A Quon	View Presentation
Trends and Technical Requirements in Electronic Packaging	Darrel Freer	View Presentation
Packaging Technology Trends and Lead Free Challenges	C. Michael Garner, Fay Hua, Nagesh Vodrahalli, Ashay Dani,	View Presentation
Reactions Between Electroless Ni(P) and Sn-3.5Ag and Its Effects on Mechanical Reliability	Tom Debonis, Raiyo Aspandiar and Yoon -Chul Sohn and Jin Yu	View Presentation
Electromigration in Flip Chip Solder Joints	J. W.Nah and K. N. Tu	View Presentation
Overview: Mechanical Properties of Pb-Free Solders	J. W. Morris, Jr.	View Presentation
Near Ternary Sn-Ag-Cu Solder Joints; Microstructure, Thermal Fatigue and Failure Mechanisms	Sung K. Kang	View Presentation
Sn-Zn Based Low Temperature Lead-Free Solder and Current Status of Lead-Free Soldering in Japan	Katsuaki Suganuma, Keun-Soo Kim, Kenji Toyofuku, Katsumi Yamamoto,	View Presentation
Nano Interconnects and Nanoscale Solder Bonding	Kouichi Hagio Sungho Jin	<u>View Presentation</u>
2005 TMS Pb-Free Technology Workshop Discussion Brief Summary	Fay Hua	View Presentation